

2020

cicor



Cicor Group – Your technology partner

At a glance

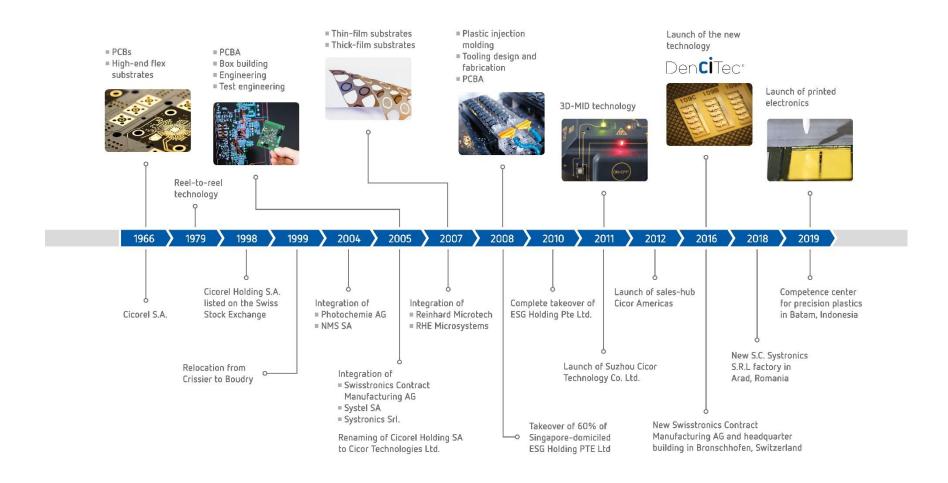
- The Swiss leader in design and manufacturing of advanced electronics
 - Advanced Microelectronics and Substrates (AMS) Division: Technology leader
 - Electronic Solutions (ES) Division: Full solution provider
- Milestones
 - 1966: Founded as manufacturer of Printed Circuit Boards (PCB)
 - 1998: Listed on the Swiss Stock Exchange
 - 2005-2008: Established the present service offerings through acquisitions
 - Since 2016: Focus on technology leadership, accelerated growth, operational excellence, lean organization
- 2,029 employees worldwide at 10 production sites in Europe and Asia





History

Building up group competencies







Leading technologies for advanced electronics

An unparalleled offering of products and services

AMS Division



ES Division



Hybrids & microelectronics

- High precision electronic substrates using a wide variety of materials and deposition processes
- Packaging and assembly of semiconductors and miniaturized electronic components

Printed circuit boards (PCB) Electronic manufacturing services (EMS)

- High-density and ultrahigh-density PCB for miniaturized electronics
- Engineering of advanced electronics
- PCB assembly, system assembly and box building
- High precision plastic injection molding and toolmaking

Printed electronics (Aerosol Jet Printing)

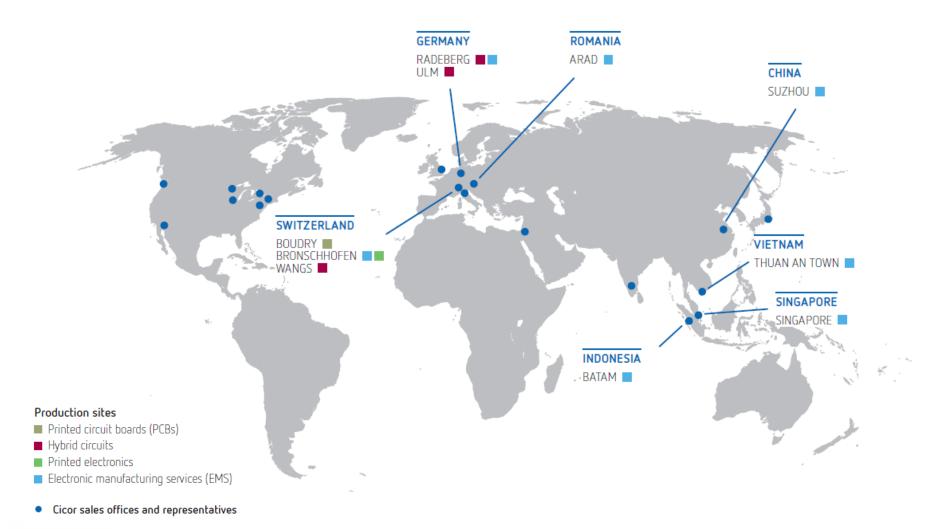
- A revolutionary technology to manufacture electronic circuits
- First to market in Europe with application lab set up in Bronschhofen in 03/2019





Global footprint

High tech and competitiveness - close to the customer







Cicor in 2018

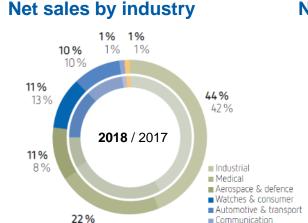
Year of high growth and successful projects

- AMS Division further increased its share of group sales to 25.4 % (2017: 24.4 %)
- Strategic markets very strong: Share of industrial, medical, aerospace & defence markets at 77.0 % (2017: 74.4 %)
- Acceleration in Europe, ROW mostly flat

AMS Division

25% 24% 2018 / 2017

Net sales by division



Other

25%







Served markets

Partnering with market and technology leaders



... and many more





Leading process capabilities

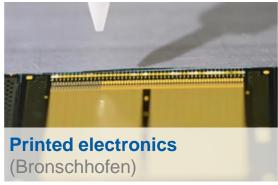
Continued investment in innovative technologies











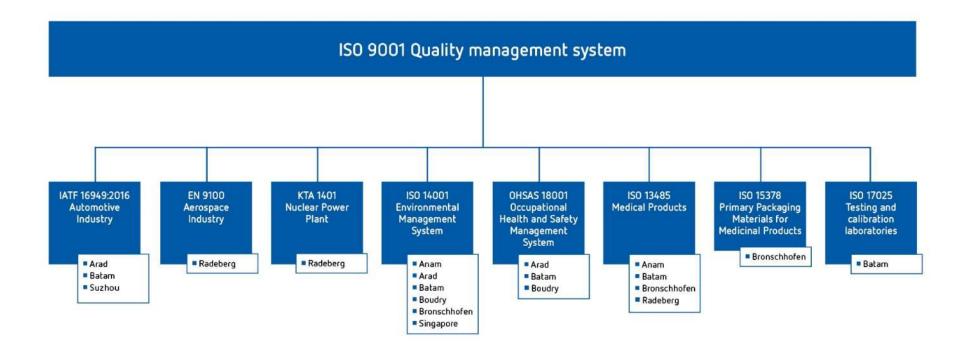






Quality management

Certificates

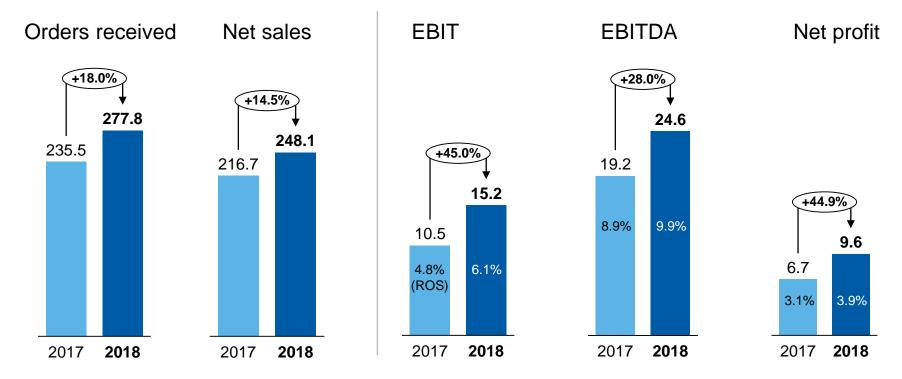






Financial achievements 2018

All figures at actual FX rates



- 2018 Book-to-bill ratio of 1.12 (2017: 1.08)
- Sales growth of 12.7% in local currencies





Conclusion

Why Cicor

Global set-up... Wide range... Scale... One partner... ...from the develop-...of services ...of ment to the ...and and production financial finished and technologies sites stability tested product





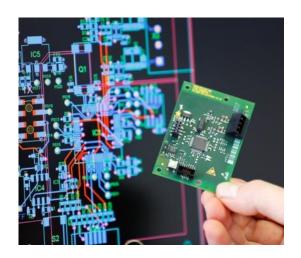
Corporate Presentation

Technologies & Services





Engineering services



- Hardware development
- Software development
- PCB layout
- Mechanics design
- Test engineering
- Project management







Printed circuit boards (PCB)

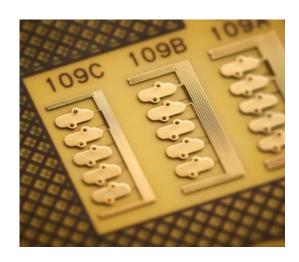


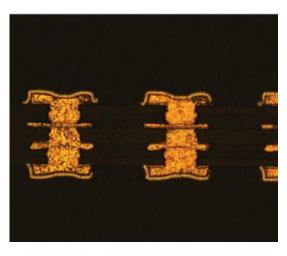
- High-end flex, rigid-flex, and rigid MLBs
- Rigid PCBs with 1-20 layers
- Impedance-controlled PCBs +/- 5%
- Panel and reel-to-reel production lines
- HDIs: laser and mechanical drilling
- Laser openings (cavities) + depth controlled routing
- Final finishing: ENIG, ENEPIG, Imm. Sn, Imm. Ag, ISIG, EPIG, OSP, electroplated Au
- Copper filled blind vias, copper filled through holes
- Lines/spaces down to 25/25 µm (1 mil)
- Microvias down to 30 µm (1.2 mil)
- Non conductive epoxy via plugging





DenciTec®





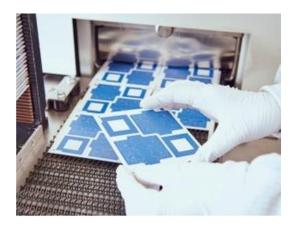
- Miniaturization
 - Lines/spaces down to 25/25 µm (1 mil) with 20 µm Cu thickness
 - Significantly higher level of integration
 For example: more volume for energy supply,
 batteries, etc.
- Higher packaging densities
 - More design options
- More functionality
 - Smarter products with more features
- Lower costs compared to other technologies
 - Economic





Hybrid circuits





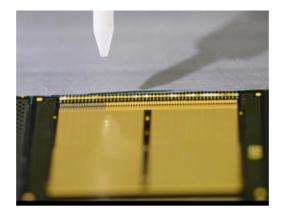
- Thin film (polymer, multilayer, ceramic, steel, glass, ferrites)
- Thin film flex boards
- Traces below 10 µm
- Cu-filled through holes
- Thick Cu
- Thick film (ceramic, steel)
- High ohmic R layer

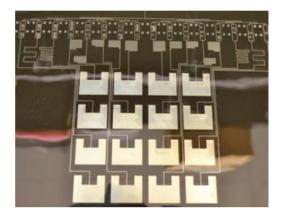




Printed electronics

Cicor Group





Technical capabilities

- Lines/spaces down to 10 µm
- Printing thickness from < 100 nm to tens of µm
- Large material portfolio (conductive, non-conductive, resistors, biocompatible, photoresist, etc.)
- Printing on standard materials
- Efficient printing process

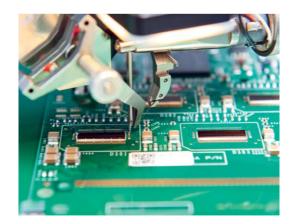
Possible applications

- Printed flex and rigid circuits
- Printed embedded passives
- Printed circuits on ceramics (2D + 3D)
- Printed circuits on plastics
- Biocompatible circuits





Electronic manufacturing services (EMS)



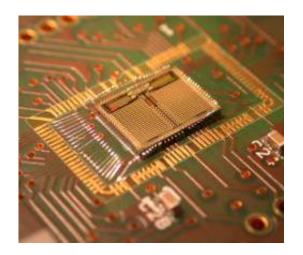


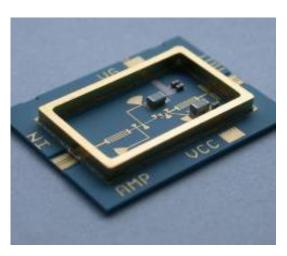
- Engineering services
- PCB assembly
- System assembly
- Box building
- Cable assembly
- Coating, potting
- Testing
- Wire bonding
- Coil winding
- Service & repair





Microelectronic assembly





- Die attach, COB, flip chip, bare die, MMICs, SMD (min. 01005), µBGA
- Wire/ribbon bonding
- Automatic ball-wedge and wedge-wedge wire bonding
- Soldering
- Packaging, glob top
- MEMS / RF MEMS packaging
- Hermetic housing (metal, ceramic)





Plastic services





- Tool design and fabrication
- Plastic injection molding (20 tons to 468 tons)
- Thin wall molding
- Insert molding
- 2k molding
- Ultrasonic welding
- Box building
- Clean room packaging
- High precision mechanical assembly
- 3D-MID technology





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